		Search Text	-	Time stamp
,			USPAT;	2003/01/11
mber_	5	TO SECULATION OF THE SECURATION OF THE SECURATIO	US-PGPUB;	15:57
	3	· ·	;	1000
\			EPO; JPO;	
		1	DERWENT;	
ļ	!		IBM_TDB	2002/01/11
		i dutor	USPAT;	2003/01/11
	0	pcb with semicondutor	US-PGPUB;	15:57
Ì			EPO; JPO;	
i			DERWENT;	
i			IBM TDB	
ŀ			USPAT;	2003/01/11
ļ	1	board with semicondutor	US-PGPUB;	15:59
	1 1	boara	EPO; JPO;	1 2 2 2 2 2
	[
		İ	DERWENT;	
			IBM_TDB	0000 (01 (11
			USPAT;	2003/01/11
	2077	((printed adj circuit adj board) or	US-PGPUB;	18:14
		((printed adj circuit adj bours, (PCB)) and (semiconductor adj substrate)	EPO; JPO;	1
			DERWENT;	1
			IBM TDB	ļ
			USPAT;	2003/01/11
	440	((printed adj circuit adj board) or		16:16
	440	((printed ad) circuit adj bodita, (PCB)) same (semiconductor adj substrate)	US-PGPUB;	13.10
		(PCB)) Same (Schiller	EPO; JPO;	
			DERWENT;	1
	}		IBM_TDB	
	ļ		USPAT;	2003/01/11
	494	((printed adj (circuit or wiring)adj	US-PGPUB;	18:14
-		1 mal or (DCB Of DWC)) Sumo	EPO; JPO;	
	j	(semiconductor adj substrate)		
		100000	DERWENT;	
	i		IBM_TDB	2003/01/11
		((printed adj (circuit or wiring)adj	USPAT;	16:19
_	0		US-PGPUB;	10:12
	Ţ	board) or (PCB of pwc) same	EPO; JPO;	
		(semiconductor adj substrate) and keypad	DERWENT;	
			IBM TDB	
		المراجع المراج	USPAT;	2003/01/11
	1	(((printed adj (circuit or wiring)adj	US-PGPUB;	16:20
-	1			
	1	(semiconductor adj substrate)) and keypad	DERWENT;	
		(Schizoomas		1
	{		IBM_TDB	2003/01/11
		(((printed adj (circuit or wiring)adj	USPAT;	1
_	38		US-PGPUB;	
		board) or (PCB or pwc)) and (semiconductor adj substrate)) and keypad	EPO; JPO;	1
	1	(semiconductor adj substract)	DERWENT;	.
			IBM TDB	
			USPAT;	2003/01/11
	997	4 ((printed adj (circuit or wiring)adj	US-PGPUB;	1
-	337	board) or (PCB or pwc)) with	EPO; JPO;	
		(semiconductor)		1
	i I	(Deut Conda a = -)	DERWENT;	Ì
			IBM_TDB	2003/01/11
	ļ	1 ((printed adj (circuit or wiring)adj	USPAT;	
i –	841	1 ((printed adj (critation)	US-PGPUB;	
		board)) with (semiconductor)	EPO; JPO;	: [
			DERWENT;	!
			IBM TDB	
	Ì	1	USPAT;	2003/01/11
	9.0	display and (((printed adj (circuit or	US-PGPUB	
_	, 89	display and (((printed dd) ()) with wiring) adj board) or (PCB or pwc)) with		, -
		(semiconductor)	EPO; JPO	'
i	ļ	(semiconductor)	DERWENT;	ì
			IBM_TDB	
!	!	1 and substrate) USPAT;	2003/01/11
i :	666	67 display and (semiconductor adj substrate	US-PGPUB	; 16:41
į –	į	· · ·	EPO; JPO	- 1
1	İ	į	DERWENT;	
İ	1			!
i	į		IBM_TDB	

	1012		·	2003/01/11
	1017		05 101027	16:41
			EPO; JPO;	
			DERWENT;	
j		Ĭ.	IBM_TDB	2222/01/11
Ì			ODITIE,	2003/01/11
ļ	3844	tor add slibstfale)	03 10102/	16:42
ļ		(semiconductor day same)	EPO; JPO;	
j			DERWENT;	
ì			IBM_TDB	
ļ		(display with (semiconductor adj	USPAT;	2003/01/11
	20	(display with (sellif-conductor day substrate)) and ((strain or pressure or	US-PGPUB;	16:47
į		keypad) with (semiconductor adj	EPO; JPO;	
ľ	į	keypad) with (semiconductor and	DERWENT;	
ļ		substrate))	IBM TDB	
		substrate same display same (pressure or	USPAT;	2003/01/11
	12	substrate same display same (pressure	US-PGPUB;	17:02
		strain or keypad) same logic	EPO; JPO;	
Į.			DERWENT;	
ļ	1		IBM TDB	
			USPAT;	2003/01/11
-	13555	touch adj panel	US-PGPUB;	17:02
] .		EPO; JPO;	
			DERWENT;	
	·		IBM TDB	
			USPAT;	2003/01/11
_	5041	method and (touch adj panel)	US-PGPUB;	17:03
			EPO; JPO;	[
			DERWENT;	
			IBM TDB	
		touch adi	USPAT;	2003/01/11
_	1727	(pressure or strain) and (touch adj	US-PGPUB;	17:03
		panel)	EPO; JPO;	
	İ		DERWENT;	1
			IBM TDB	
		and strain) and	USPAT;	2003/01/11
_	512	substrate and ((pressure or strain) and	US-PGPUB;	17:11
		(touch adj panel))	EPO; JPO;	
	i		DERWENT;	
			IBM TDB	
		light with	USPAT;	2003/01/11
_	2056		US-PGPUB;	17:12
		emitting)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
			USPAT;	2003/01/11
_	49270	substrate and ((gaas with light with	US-PGPUB;	17:13
	[emitting) or led)	EPO; JPO;	
	ļ		DERWENT;	
			IBM TDB	
		i all substrates and ((daas	USPAT;	2003/01/11
-	4878	(semiconductor adj substrate) and ((gaas	US-PGPUB;	17:14
		with light with emitting) or led)	EPO; JPO;	
			DERWENT;	1
į			IBM TDB	
				2003/01/11
_	106132	strain and (logic or control or computer)	US-PGPUB;	17:15
	ļ.		EPO; JPO;	
!			DERWENT;	
ļ		 	IBM_TDB	
Į		i control or	USPAT;	2003/01/11
! _	2905	5 strain same (logic or control or	US-PGPUB;	17:16
1	i	computer)	EPO; JPO;	
i			DERWENT;	
i I	ļ	·	IBM TDB	
Į.	į.			2003/01/11
! _	2	9 ((semiconductor adj substrate) and ((gaa	US-PGPUB;	
;		- I with 13 wht with Amiltilian Or 1997, with	EPO; JPO	
1	į	(strain same (logic or control of	DERWENT;	
i	İ	computer))	IBM TDB	
				the second of th

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_	3867	processor and strain and display	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/11 17:54
-	169	processor same strain same display	IBM TDB USPAT; US-PGPUB; EPO; JPO;	2003/01/11 17:33
	16	substrate and (processor same strain same display)	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/01/11 17:55
_	892	substrate and (processor and strain and display)	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/01/11 17:42
_	33527	processor and sensor and display	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/01/11 17:55
_	47084	(microprocessor or processor) and sensor	EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/01/11
_		and display	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	17:56
_	5896	substrate and ((microprocessor or processor) and sensor and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	17:56
_	100	substrate with ((microprocessor or processor) and sensor and display)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/11 18:13
-	1440	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with silicon	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/11 18:15
-	159	((printed adj (circuit or wiring)adj board) or (PCB or pwc)) with silicon adj substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/11 18:16
-	9	((thermal or pressure or strain or chemical) with sensor) and (gaas with (junction or pn adj junction))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/12 15:27
-	20845	((thermal or pressure or strain or chemical) with sensor) and (display)	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/01/12 15:28
-	10529	((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/01/12 15:30
-	2033	semiconductor and (((thermal or pressure or strain or chemical) with sensor) and (display) and (microprocessor or processor or logic))	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/12 15:31

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			USPAT;	2003/01/12 15:52
T-	750 sı		US-PGPUB;	15.54
	(((thermal or pressure of solar) and	EPO; JPO;	
	c c	hemical) with sensor) and (display) microprocessor or processor or logic)))	DERWENT; IBM TDB	
	1 (MTGTObtoggggg a= t	USPAT;	2003/01/12
	31 0	ommon adjl substrate and (semiconductor	US-PGPUB;	16:30
	a	nd (((thermal of pressure /display) and	EPO; JPO;	
į		nd (((thermal or pressure of state) themical) with sensor) and (display) and themical) with sensor processor or logic)))	DERWENT;	
	1	hemical) with sensor) and (display) hemical) with sensor) and (display) hemicroprocessor or processor or logic)))	IBM_TDB	2003/01/12
	ì		USPAT;	17:02
	266 f	Flannery.in.	US-PGPUB; EPO; JPO;	<u> </u>
	ļ		DERWENT;	
ļ	l		IBM_TDB	1
	1	4-	USPAT;	2003/01/12
	31	michael.in. and flannery.in.	US-PGPUB;	17:11
	J.		EPO; JPO;	
	ļ		DERWENT;	
	1		IBM_TDB USPAT;	2003/01/12
Ì		(circuit adj board) with (silicon or	USPAT; US-PGPUB;	17:16
-	16354	semiconductor)	EPO; JPO;	
	ł	Seminary	DERWENT;	
	}		IBM_TDB	2003/01/12
l		y hand) with (silicon or	USPAT;	17:17
_	132	(circuit adj board) with (silicon or semiconductor) adj (material or layer)	US-PGPUB;	11.11
	ļ	semiconductor, adj (macozza	EPO; JPO; DERWENT;	
			IBM TDB	
			USPAT;	2003/01/12
,	132	(circuit adj board) with ((silicon or	US-PGPUB;	17:43
-	132	(circuit adj board) With ((Silloud)) semiconductor) adj (material or layer))	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	2003/01/12
		(display or lcd) same substrate same	USPAT; US-PGPUB;	_
-	80	(display or 1cd) same substrate Same (microprocessor or logic) same (sensor o	EPO; JPO	
		1 , and or thermal or borne	DERWENT;	
		microelectromechanical	IBM_TDB	0000/01/12
		micromechanical)	h USPAT;	2003/01/12
_	26	(display or lcd) same (semiconductor) substrate) same (microprocessor or logic substrate) same (semical or thermal or) US-PGPUB	, =
		substrate) same (microproced or thermal or	EPO; JPO DERWENT;	′
 	1	same (sensor of chemical or strain or microelectromechanical or	IBM TDB	
			USPAT;	2003/01/18
l I	80608		US-PGPUE	3; 20:04
-	80806	sensor same (strain of the chemically or chemical or radiation)	EPO; JPC);
			DERWENT;	
	į		IBM_TDB	2003/01/18
		display same (pixel or pixels)	USPAT;	00
-	6330	/ display Same (P	EPO; JP	J, _
			DERWENT	;
			IBM_TDB	\
1	ļ	thermal or	USPAT;	2003/01/18
-	1841	6 (sensor same (strain or thermal or chemically or chemical or radiation)) a chemically or chemical or radiation)	nd US-PGPU	
_	_	chemically or chemical of ladar logic) (microprocessor or processor or logic)	EPO; JP	
		(microprocessor of product	DERWENT IBM TDE	
			USPAT;	2003/01/10
	2100	display same (pixel or pixels)) and (display same (pixel or processor or logic)	US-PGPU	02
-	2188	(display same (pixel of pixel) (microprocessor or processor or logic)	EPO; JI	
	Ì	,	DERWENT	Γ;
	ļ		IBM_TDI	B 2003/01/18
i	i	3 (sensor same (strain or thermal or	USPAT;	
i –	į	3 (sensor same (strain of the lattice)) chemically or chemical or radiation))	US-PGP EPO; J	00,
		chemically or chemical of radiation same (display same (pixel or pixels))	DERWEN	
1	i	same wafer	IBM_TD	В
	į		r	• •
-	1	graphical and the second of th		
		1/18703 10:05:10 PM Page 4		

[742	((sensor same (strain or thermal or chemically or chemical or radiation)) and (microprocessor or processor or logic))	USPAT; US-PGPUB; EPO; JPO;	2003/01/18 20:04	
7	91	and ((display same (pixel or pixels)) and (microprocessor or processor or logic)) wafer and (((sensor same (strain or	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/18 20:04	